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(19)



JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

(11) Publication number: 200127271

(43) Date of publication of application: 05.10.2

(51) Int. Cl. G03F 7/039

C08K 5/09, C08K 5/17, C08K 5/36, C08L 25/18, G03F 7/004,
H01L 21/027

(21) Application number: 2000084470

(22) Date of filing: 24.03.2000

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(54) POSITIVE TYPE RADIATION SENSITIVE
RESIN COMPOSITION

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a positive type radiation sensitive resin composition which improves line edge roughness(LER), has high sensitivity and high resolving power and ensures improved surface roughness of a resist pattern.

SOLUTION: The positive type radiation sensitive composition contains at least (a) a resin having, which is decomposed by the action of an acid creases solubility in an alkali developing solution, a compound which generates the acid when irradiated with active light or radiation, (c) an organic carboxylic acid compound, (d) a basic compound and (e) a surfactant.

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